

/ Descriptions

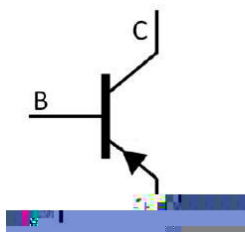
SOT-23 PNP

/ Features

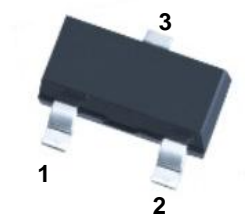
BCW32

/ Applications

/ Equivalent Circuit

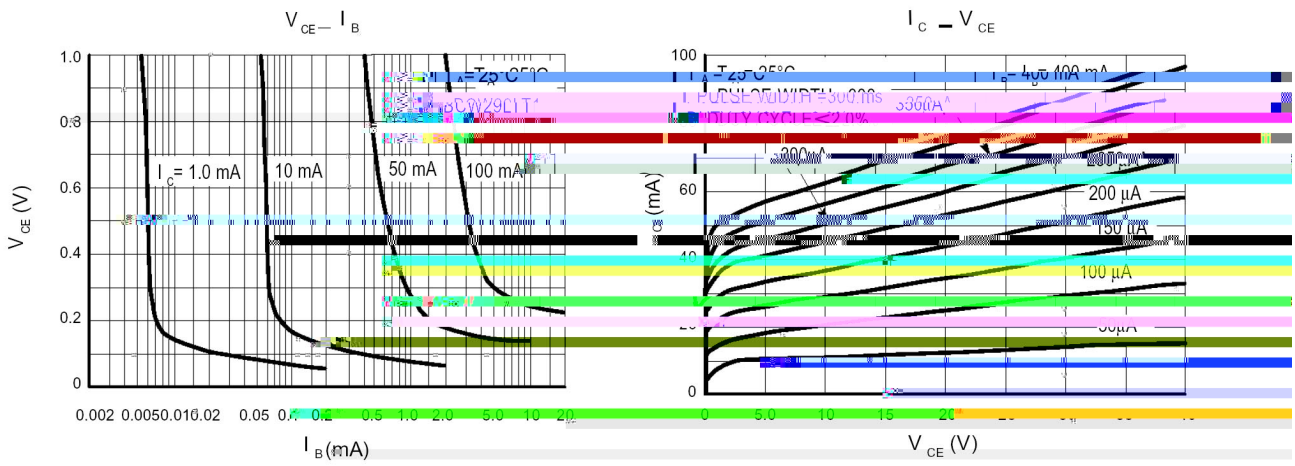
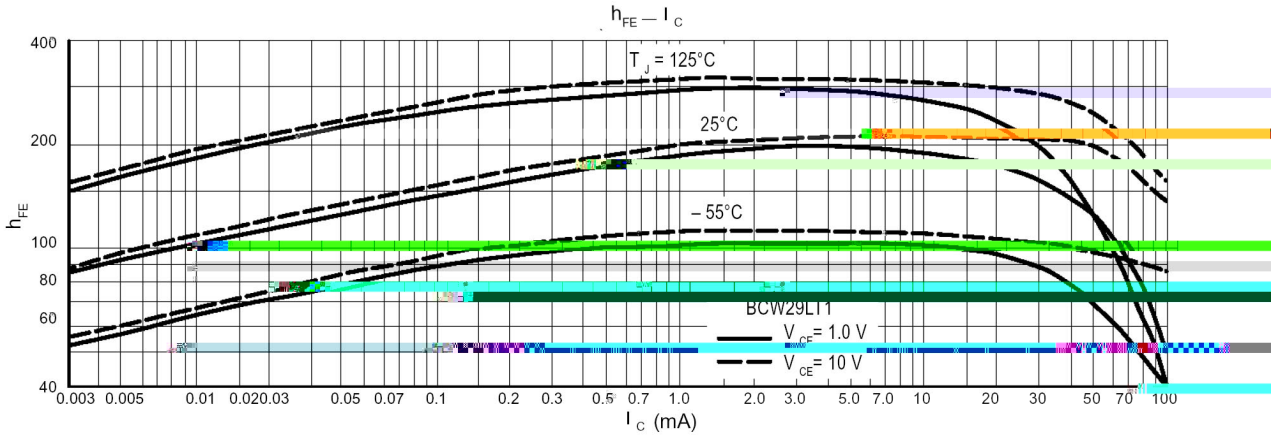


/ Pinning



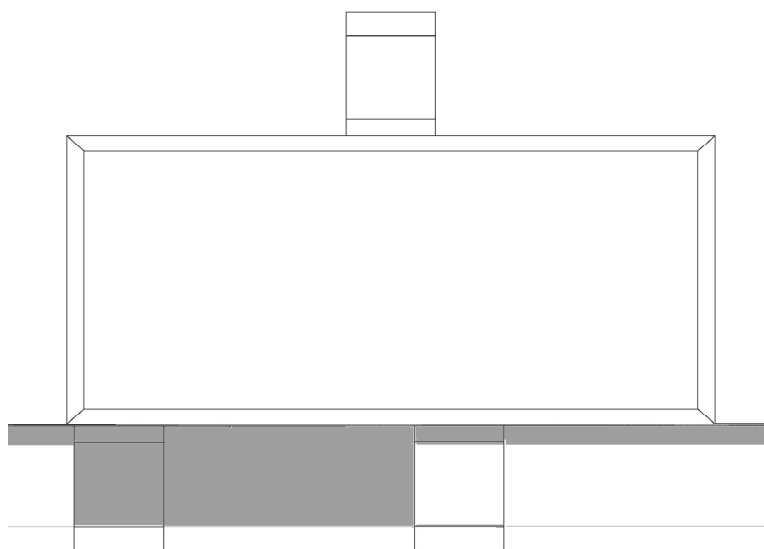
/ h_{FE} Classifications & Marking

/ Electrical Characteristic Curve

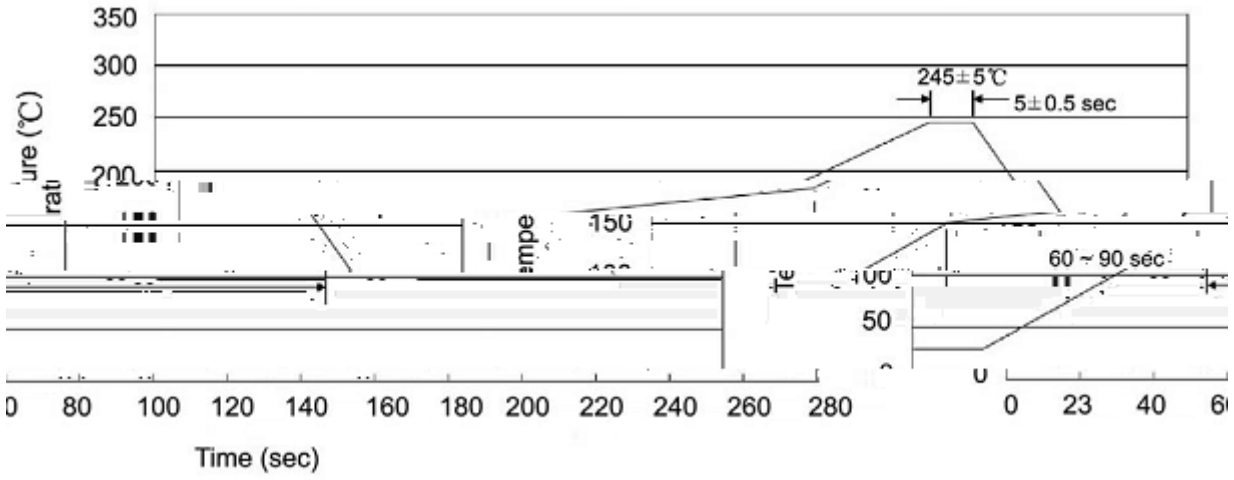


BCW30

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只卷盘	卷盘盒	只盒	盒箱	只箱	盒	箱	

/ Notices